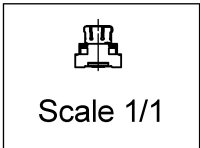
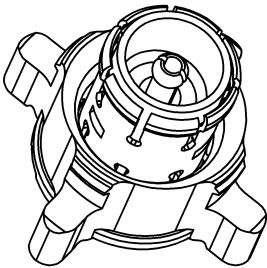
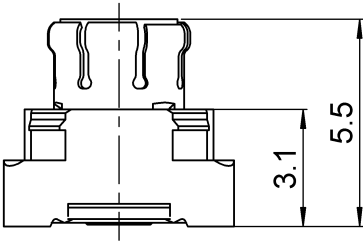
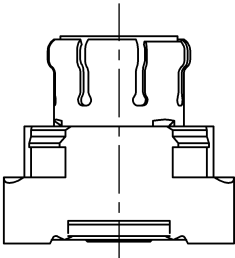
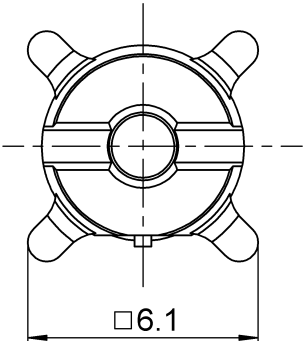
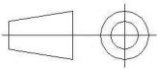


|          |                 |             |                        |
|----------|-----------------|-------------|------------------------|
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|----------|-----------------|-------------|------------------------|



All dimensions are in mm.



| COMPONENTS     | MATERIALS                      | PLATING (μm) |
|----------------|--------------------------------|--------------|
| Body           | <b>BERYLLIUM COPPER; BRASS</b> | <b>NPGR</b>  |
| Center contact | <b>BERYLLIUM COPPER; BRASS</b> | <b>NPGR</b>  |
| Outer contact  | -                              |              |
| Insulator      | <b>PTFE</b>                    |              |
| Gasket         |                                |              |
| Others parts   |                                |              |
| -              | -                              | -            |
| -              | -                              | -            |

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SERIES **MMBX**

PART NUMBER **R223434000**

## PACKAGING

| Standard   | Unit              | Other             |
|------------|-------------------|-------------------|
| <b>100</b> | <b>Contact us</b> | <b>Contact us</b> |

## ELECTRICAL CHARACTERISTICS

|                                 |              |               |                             |
|---------------------------------|--------------|---------------|-----------------------------|
| Impedance                       |              | <b>50</b>     | $\Omega$                    |
| Frequency                       |              | <b>0-12.4</b> | GHz                         |
| VSWR                            | <b>1.065</b> | <b>+</b>      | <b>0.0000</b> x F(GHz) Maxi |
| Insertion loss                  |              | <b>0.12</b>   | $\sqrt{F}$ (GHz) dB Maxi    |
| RF leakage                      | - (          | <b>100</b>    | - F(GHz)) dB Maxi           |
| Voltage rating                  |              | <b>330</b>    | Veff Maxi                   |
| Dielectric withstanding voltage |              | <b>1000</b>   | Veff mini                   |
| Insulation resistance           |              | <b>1000</b>   | M $\Omega$ mini             |

## MECHANICAL CHARACTERISTICS

|                            |  |               |             |
|----------------------------|--|---------------|-------------|
| Center contact retention   |  |               |             |
| Axial force – Mating End   |  | <b>10</b>     | N mini      |
| Axial force – Opposite end |  | <b>10</b>     | N mini      |
| Torque                     |  | <b>NA</b>     | N.cm mini   |
| Recommended torque         |  |               |             |
| Mating                     |  | <b>NA</b>     | N.cm        |
| Panel nut                  |  | <b>NA</b>     | N.cm        |
| Mating life                |  | <b>100</b>    | Cycles mini |
| Weight                     |  | <b>0.3960</b> | g           |

## ENVIRONMENTAL

|                       |                 |           |
|-----------------------|-----------------|-----------|
| Operating temperature | <b>-55/+155</b> | °C        |
| Hermetic seal         | <b>NA</b>       | Atm.cm3/s |
| Panel leakage         | <b>NA</b>       |           |

## SPECIFICATION

## OTHER CHARACTERISTICS

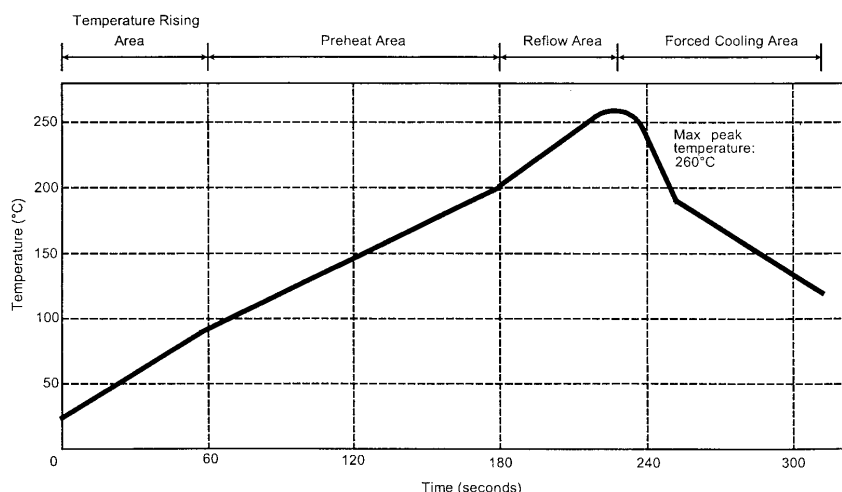
Assembly instruction:

Others:  
**to 2GHz (1.106 --- 2 to 6GHz)**  
**Interface MMBX only ,up to 2.5GHz**  
**PCB to PCB -45 dB up to 2.5 GHz**

## SOLDER PROCEDURE OF MMBX RECEPTACLE IN INDUSTRIAL ENVIRONMENT

1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application.  
We recommend a low residue flux.  
We advise a thickness of 150 micromm ( 5.850 microinch ). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.  
A video camera is recommended for positioning of the component.  
Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven.  
Below please find, the typical profile to use.
4. The cleaning of printed circuit boards is not obliged.
5. Verification of solder joints and position of the component by visual inspection.

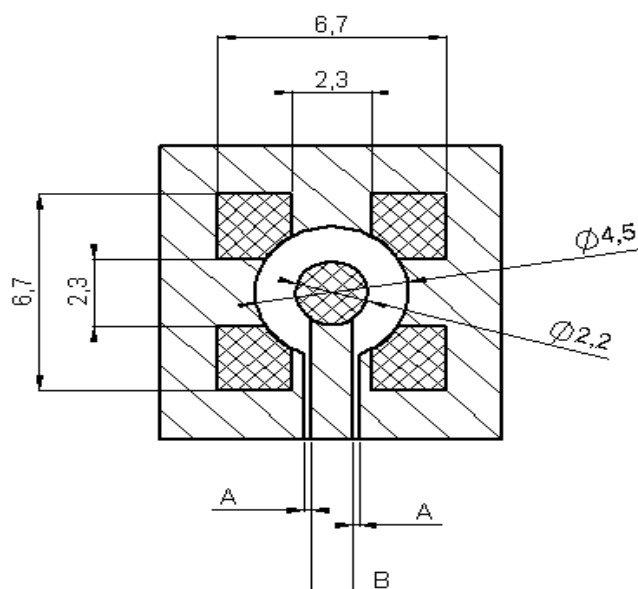
### TEMPERATURE PROFILE



| Parameter                        | Value     | Unit   |
|----------------------------------|-----------|--------|
| Temperature rising Area          | 1 - 4     | °C/sec |
| Max Peak Temperature             | 260       | °C     |
| Max dwell time @260°C            | 10        | sec    |
| Min dwell time @235°C            | 20        | sec    |
| Max dwell time @235°C            | 60        | sec    |
| Temperature drop in cooling Area | -1 to - 4 | °C/sec |
| Max dwell time above 100°C       | 420       | sec    |

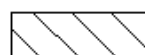
# MMBX SERIES INFORMATIONS

## PCB



### COPLANAR LINE

Pattern and signal are on the same side  
The material of PCB is epoxy resin (FR4).  
(Er = 4.6)  
The solder resist should be printed  
Except for the land pattern on the PCB



**Pattern**



**Land for solder paste**

### APPLICATION 75Ω

**WITH B = 0,55mm**

| PCB thickness (mm) | Coplanar ligne A (mm) |
|--------------------|-----------------------|
| 0,8                | 0,350                 |
| 1,0                | 0,360                 |
| 1,2                | 0,365                 |
| 1,6                | 0,375                 |

### APPLICATION 50Ω

**WITH B = 1,2mm**

| PCB thickness (mm) | Coplanar ligne A (mm) |
|--------------------|-----------------------|
| 0,8                | 0,190                 |
| 1,0                | 0,200                 |
| 1,2                | 0,205                 |
| 1,6                | 0,210                 |

# MMBX SERIES INFORMATIONS

